



Material Content Data Sheet



Sales Product Name	TLE42764D V50			Issued	31. July 2018			
MA#	MA001140440							
Package	PG-TO252-5-11			Weight*	365.99 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.179	0.87	0.87	8686	8686
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		168	
	non noble metal	iron	7439-89-6	0.205	0.06		559	
	non noble metal	copper	7440-50-8	204.243	55.79	55.87	558055	558782
	non noble metal	aluminium	7429-90-5	0.185	0.05	0.05	506	506
wire	non noble metal	aluminium	7429-90-5	0.185	0.05	0.05	506	506
encapsulation	organic material	carbon black	1333-86-4	0.296	0.08		810	
	plastics	epoxy resin	-	13.630	3.72		37242	
	inorganic material	silicondioxide	60676-86-0	134.227	36.68	40.48	366752	404804
leadfinish	non noble metal	tin	7440-31-5	5.072	1.39	1.39	13860	13860
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	208	209
solder	non noble metal	tin	7440-31-5	0.096	0.03		263	
	noble metal	silver	7440-22-4	0.120	0.03		329	
	non noble metal	lead	7439-92-1	4.597	1.26	1.32	12561	13153
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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